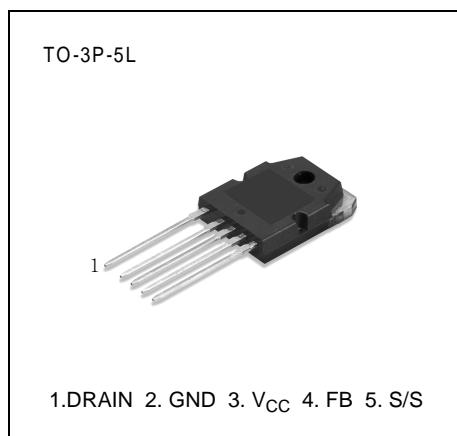


S P S

The SPS product family is specially designed for an off-line SMPS with minimal external components. The SPS consist of high voltage power SenseFET and current mode PWM IC.

Included PWM controller features integrated fixed oscillator, under voltage lock out, leading edge blanking, optimized gate turn-on/turn-off driver, thermal shut down protection, over voltage protection, and temperature compensated precision current sources for loop compensation and fault protection circuitry. Compared to discrete MOSFET and controller or RCC switching converter solution, a SPS can reduce total component count, design size, weight and at the same time increase efficiency, productivity, and system reliability.

It has a basic platform well suited for cost effective design in either a flyback converter or a forward converter.



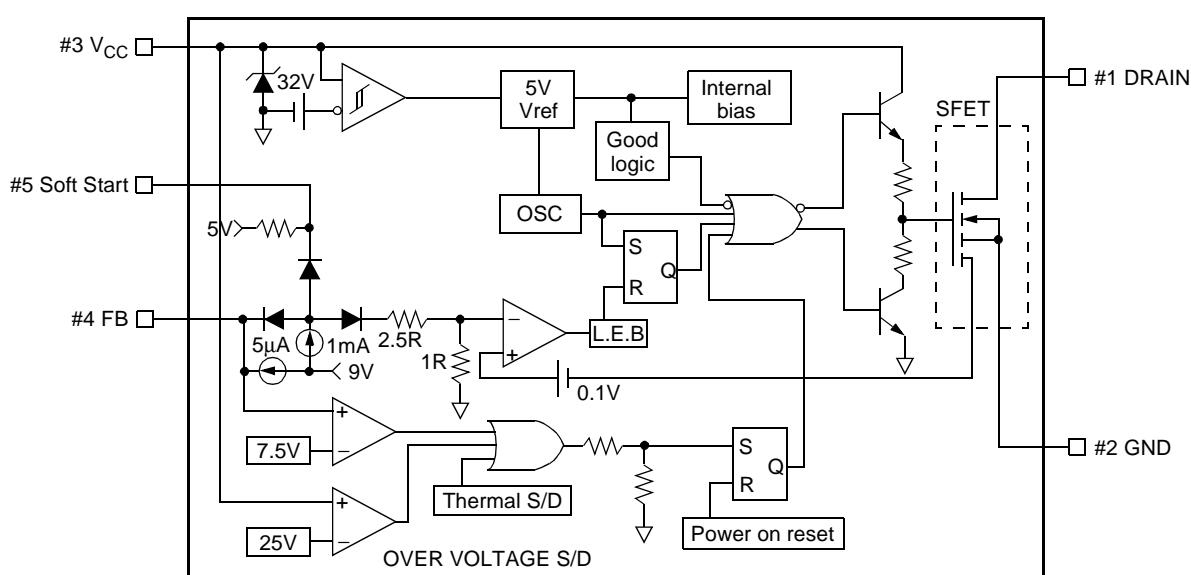
FEATURES

- Precision fixed operating frequency (70kHz)
- Pulse by pulse over current limiting
- Over current protection
- Over voltage protection (Min. 23V)
- Internal thermal shutdown function
- Under voltage lockout
- Internal high voltage sense FET
- Latch up mode
- Soft start

ORDERING INFORMATION

Device	Package	Operating Temperature
KA1M0880B	TO-3P-5L	-25°C to +85°C

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Characteristic	Symbol	Value	Unit
Drain-source (GND) voltage ⁽¹⁾	V _{DSS}	800	V
Drain-Gate voltage ($R_{GS}=1M\Omega$)	V _{DGR}	800	V
Gate-source (GND) voltage	V _{GS}	± 30	V
Drain current pulsed ⁽²⁾	I _{DM}	32.0	A _{DC}
Single pulsed avalanche energy ⁽³⁾	E _{AS}	810	mJ
Avalanche current ⁽⁴⁾	I _{AS}	25	A
Continuous drain current ($T_C=25^\circ C$)	I _D	8.0	A _{DC}
Continuous drain current ($T_C=100^\circ C$)	I _D	5.6	A _{DC}
Supply voltage	V _{CC}	30	V
Analog input voltage range	V _{FB}	-0.3 to V _{SD}	V
Total power dissipation	P _D (watt H/S)	190	W
	Derating	1.54	W/°C
Operating temperature	T _{OPR}	-25 to +85	°C
Storage temperature	T _{STG}	-55 to +150	°C

NOTES:

1. T_j=25°C to 150°C
2. Repetitive rating: Pulse width limited by maximum junction temperature
3. L=24mH, starting T_j=25°C
4. L=13uH, starting T_j=25°C

ELECTRICAL CHARACTERISTICS (SFET part)

(Ta=25°C unless otherwise specified)

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =50μA	800	—	—	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =Max., Rating, V _{GS} =0V	—	—	50	μA
		V _{DS} =0.8Max., Rating, V _{GS} =0V, T _C =125°C	—	—	200	μA
Static drain-source on resistance ^(note)	R _{DS(ON)}	V _{GS} =10V, I _D =5.0A	—	1.2	1.5	Ω
Forward transconductance ^(note)	g _f s	V _{DS} =15V, I _D =5.0A	1.5	2.5	—	mho
Input capacitance	C _{iss}	V _{GS} =0V, V _{DS} =25V, f=1MHz	—	2460	—	pF
Output capacitance	C _{oss}		—	210	—	
Reverse transfer capacitance	C _{rss}		—	64	—	
Turn on delay time	t _{d(on)}	V _{DD} =0.5BV _{DSS} , I _D =8.0A (MOSFET switching time are essentially independent of operating temperature)	—	—	90	nS
Rise time	t _r		—	95	200	
Turn off delay time	t _{d(off)}		—	150	450	
Fall time	t _f		—	60	150	
Total gate charge (gate-source+gate-drain)	Q _g	V _{GS} =10V, I _D =8.0A, V _{DS} =0.5BV _{DSS} (MOSFET switching time are essentially independent of operating temperature)	—	—	150	nC
Gate-source charge	Q _{gs}		—	20	—	
Gate-drain (Miller) charge	Q _{gd}		—	70	—	

NOTE: Pulse test: Pulse width ≤ 300μS, duty cycle ≤ 2%

ELECTRICAL CHARACTERISTICS (Control part)

(Ta=25°C unless otherwise specified)

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
REFERENCE SECTION						
Output voltage ⁽¹⁾	Vref	Ta=25°C	4.80	5.00	5.20	V
Temperature Stability ⁽¹⁾⁽²⁾	Vref/ΔT	-25°C≤Ta≤+85°C	-	0.3	0.6	mV/°C
OSCILLATOR SECTION						
Initial accuracy	Fosc	Ta=25°C	61	67	73	kHz
Frequency change with temperature ⁽²⁾	ΔF/ΔT	-25°C≤Ta≤+85°C	-	±5	±10	%
PWM SECTION						
Maximum duty cycle	Dmax	-	74	77	80	%
FEEDBACK SECTION						
Feedback source current	I _{FB}	Ta=25°C, 0V≤V _{fb} ≤3V	0.7	0.9	1.1	mA
Shutdown delay current	I _{delay}	Ta=25°C, 5V≤V _{fb} ≤V _{SD}	4.0	5.0	6.0	μA
OVER CURRENT PROTECTION SECTION						
Over current protection	I _{L(max)}	Max. inductor current	4.40	5.00	5.60	A
UVLO SECTION						
Start threshold voltage	V _{th(H)}	-	14	15	16	V
Minimum operating voltage	V _{th(L)}	After turn on	9	10	11	V
TOTAL STANDBY CURRENT SECTION						
Start current	I _{ST}	V _{CC} =14V	0.1	0.3	0.45	mA
Operating supply current (control part only)	I _{OPR}	Ta=25°C	6	12	18	mA
V _{CC} zener voltage	V _Z	I _{CC} =20mA	30	32.5	35	V
SHUTDOWN SECTION						
Shutdown Feedback voltage	V _{SD}	-	6.9	7.5	8.1	V
Thermal shutdown temperature (T _j) ⁽¹⁾	T _{SD}	-	140	160	-	°C
Over voltage protection voltage	V _{OVP}	-	23	25	28	V

NOTES:

1. These parameters, although guaranteed, are not 100% tested in production
2. These parameters, although guaranteed, are tested in EDS (wafer test) process

TYPICAL PERFORMANCE CHARACTERISTICS

(These characteristic graphs are normalized at $T_a=25^{\circ}\text{C}$)

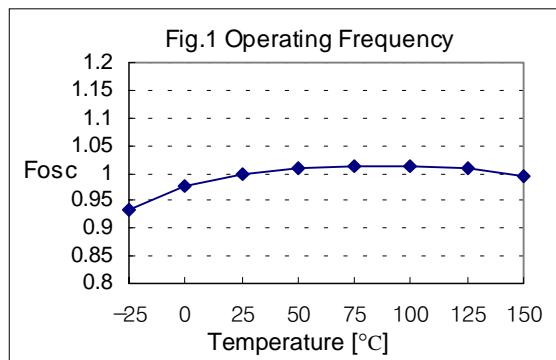


Figure 1. Operating Frequency

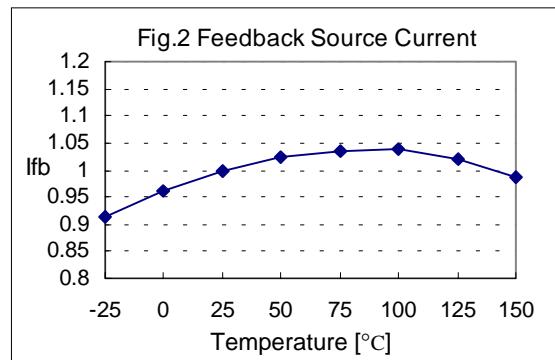


Figure 2. Feedback Source Current

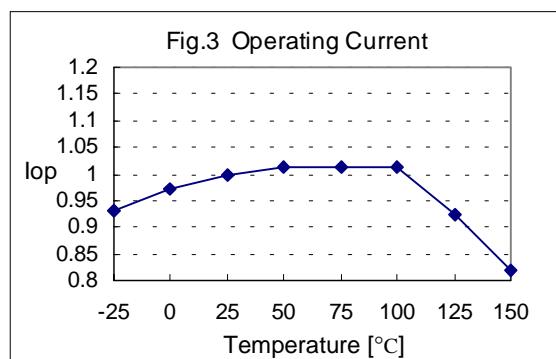


Figure 3. Operating Current

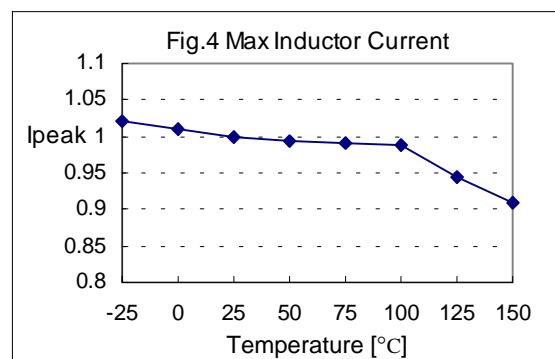


Figure 4. Max. Inductor Current

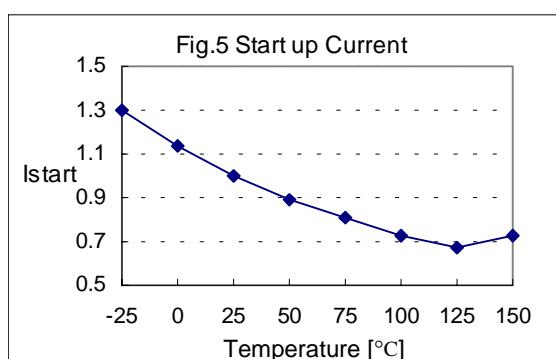


Figure 5. Start up Current

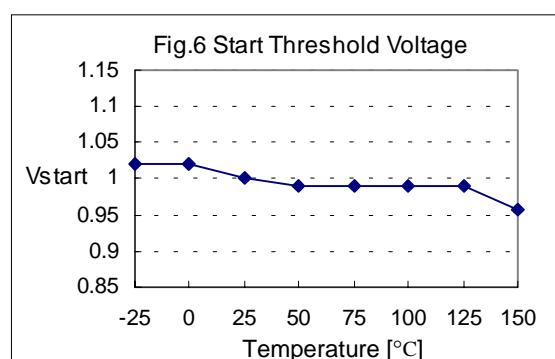
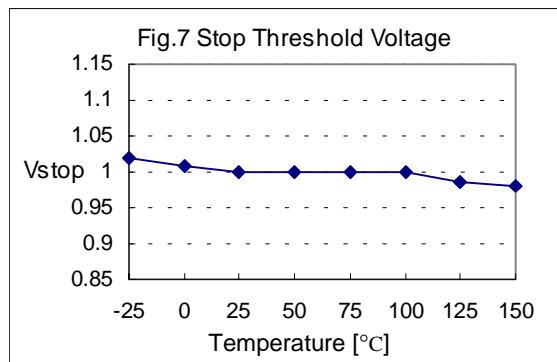
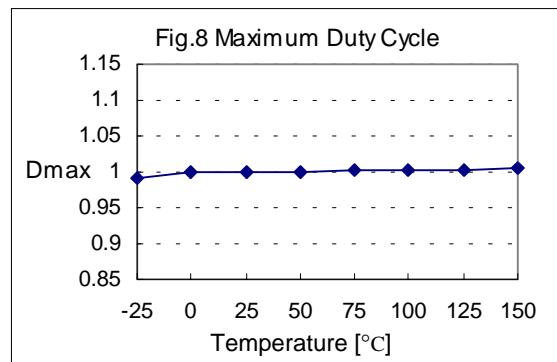
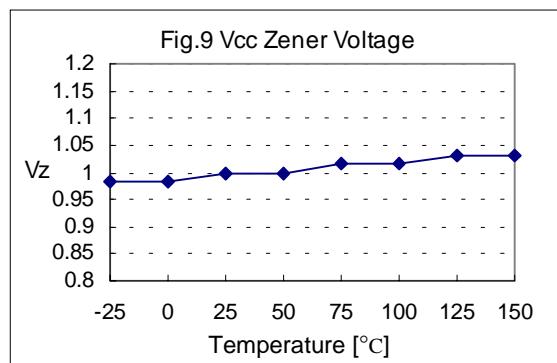
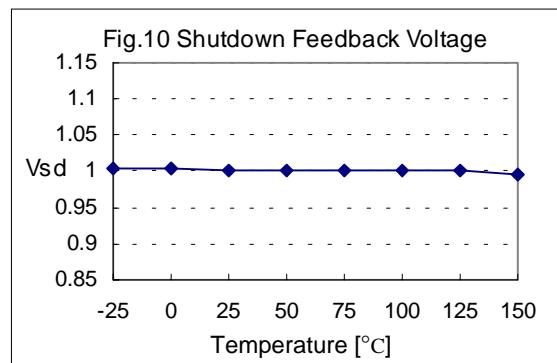
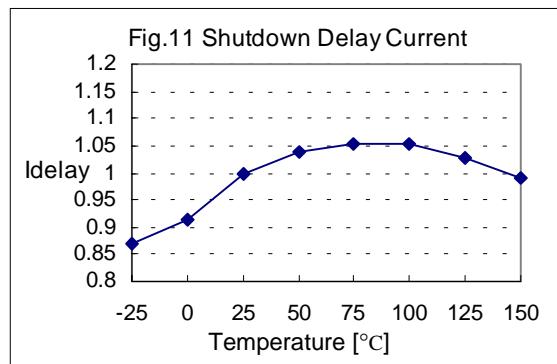
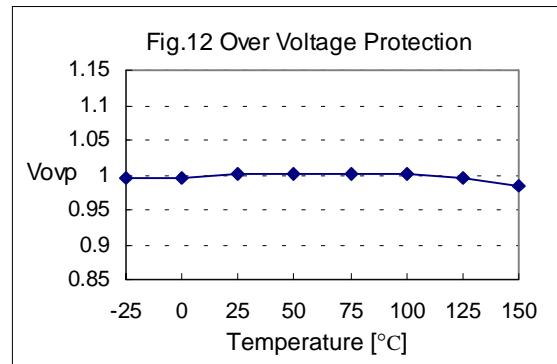


Figure 6. Start Threshold Voltage

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)(These characteristic graphs are normalized at $T_a=25^{\circ}\text{C}$)**Figure 7. Stop Threshold Voltage****Figure 8. Maximum Duty Cycle****Figure 9. V_{CC} Zener Voltage****Figure 10. Shutdown Feedback Voltage****Figure 11. Shutdown Delay Current****Figure 12. Over Voltage Protection**

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(These characteristic graphs are normalized at $T_a=25^{\circ}\text{C}$)

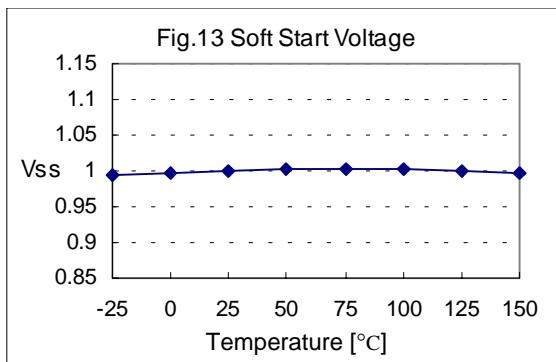


Figure 13. Soft Start Voltage

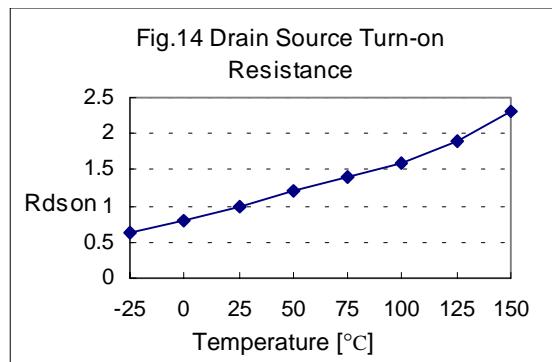


Figure 14. Drain Source Turn-on Resistance

LIFE SUPPORT POLICY

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